

MJ N-Channel Enhancement Mode Power MOSFET

Description

The MJ3035G uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Application

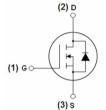
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Secondary side synchronous rectifier

High side switch in POL DC/DC converter

General Features

- VDs=30V,ID=35A
 RDS(0N)<7mΩ @ VGs=10V
 RDS(0N)<12mΩ @ VGs=4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high Eas
- Excellent package for good heat dissipation
- Special process technology for high ESD capability





s[11

MJ

DFN 5x6 EP top view

Schematic diagram

Marking and pin assignment

100% UIS TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ3035G	MJ3035G	DFN 5x6 EP	-	-	-

Absolute Maximum Ratings (Tc =25 °Cunless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	35	А
Pulsed Drain Current	lом	120	А
Maximum Power Dissipation	PD	40	W
Derating factor		0.32	W/°C
Single pulse avalanche energy (Note 5)	Eas	150	mJ
Operating Junction and Storage Temperature Range	Тյ ,Tsтg	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	Rejc	3.1	°C/W	
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Electrical Characteristics (Tc =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Uni
Off Characteristics		1	1		1	
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	30	33	-	V
Zero Gate Voltage Drain Current	loss	Vds=30V,Vgs=0V	-	-	1	μA
Gate-Body Leakage Current	lgss	VDS=±20V,VDS=0V	-	-	±100	nA
On Characteristics (Note 3)	I		1			
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	1	1.6	3	V
		V _{GS} =10V, I _D =12A	-	5.9	7.0	mΩ
Drain-Source On-State Resistance	Rds(on)	Vgs=4.5V, Id=10A	-	8.9	12.0	mΩ
Forward Transconductance	gfs	V _{DS} =10V,I _D =12A	30	-	-	S
Dynamic Characteristics ^(Note 4)	I	1		1	1	1
Input Capacitance	Clss	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	2330	-	PF
Output Capacitance	Coss		-	460	-	PF
Reverse Transfer Capacitance	Crss		-	230	-	PF
Switching Characteristics (Note 4)	I	1	1			
Turn-on Delay Time	td(on)		-	18	-	nS
Turn-on Rise Time	tr	Vdd=15V,Id=12A	-	10	-	nS
Turn-Off Delay Time	td(off)	VDD=15V,ID=12A Vgs=10V,Rgen=6Ω	-	34	-	nS
Turn-Off Fall Time	tr		-	10	-	nS
Total Gate Charge	Qg		-	45	-	nC
Gate-Source Charge	Qgs	V _{DS} =15V,I _D =12A, V _{GS} =10V	-	13	-	nC
Gate-Drain Charge	Qgd	_	-	10	-	nC
Drain-Source Diode Characteristics	I	1	<u> </u>	1	<u> </u>	1
Diode Forward Voltage (Note 3)	Vsd	V _{GS} =0V,Is=12A	-	0.85	1.2	V
Diode Forward Current ^(Note 2)	ls		-	-	35	A
Reverse Recovery Time	trr	TJ=25°C, IF=12A di/dt=100A/μs ^(Note 3)	-	-	47	nS
Reverse Recovery Charge	Qrr		-	-	25	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is n	egligible(tu	urn-on is d	ominated b	y LS+l

Notes:

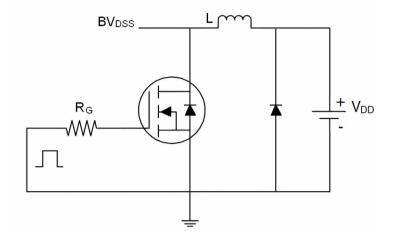
- ① Repetitive Rating: Pulse width limited by maximum junction temperature.
- ② Surface Mounted on FR4 Board, t≤10sec.
- ③ Pulse Test: Pulse Width≤300µs, Duty Cycle≤2%.
- ④ Guaranteed by design, not subject to production
- (5) EAS condition: Tj=25°C,V_DD=15V,V_G=10V,L=0.1mH,Rg=25\Omega



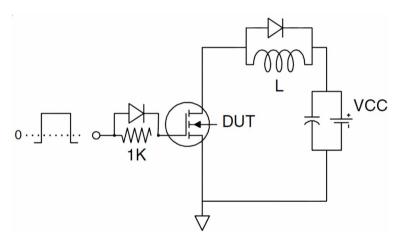




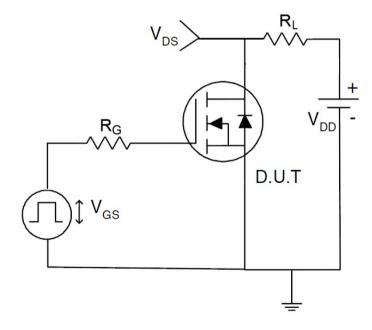
Test circuit



EAs test Circuit



Gate charge test Circuit



Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

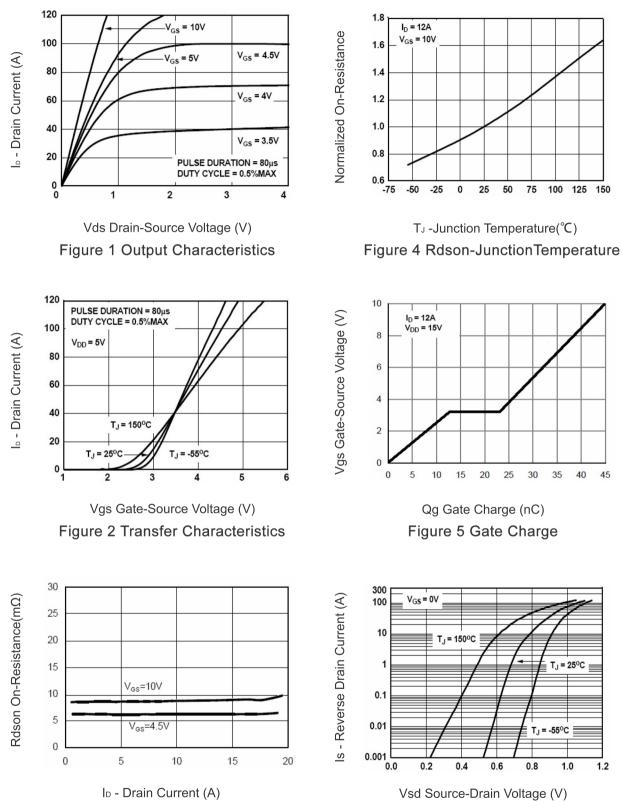


Figure 6 Source- Drain Diode Forward

Figure 3 Rdson- Drain Current







TJ(°C)

TJ(°C)

10³

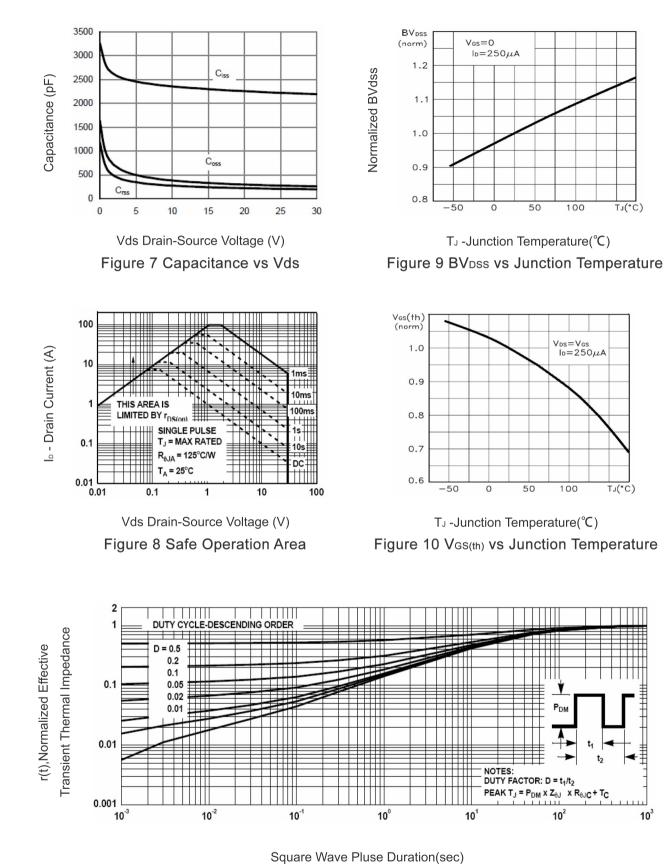


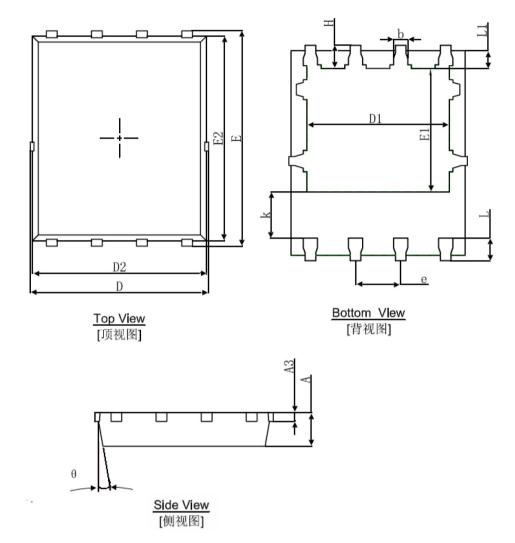
Figure 11 Normalized Maximum Transient Thermal Impedance

http://www.mjxdz.com









Cumula	Dimensions	In Millimeters	Dimension	s in inches
Symbol	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254	REF.	0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
е	1.270	TYP.	0.050	TYP.
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
Н	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°





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